

ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®

Material Composition Declaration
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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard http://www.ipc.org/IPC-175x

Form Type\*
Distribute

**Declaration Class\*** Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infomation

Supplier Information			
Company Name *	Company Unique ID		Response Date*
Fairchild Semiconductor	00-489-5751	Dun & Bradstreet	Sat, Sep 28, 2013 03:35 AM
Contact Name *	Title - Contact	Phone - Contact *	Email - Contact *
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Authorized Representative *	Title - Representative	Phone - Representative *	Email - Representative *
David Lancaster	Product Ecology	801-562-7455	david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Ite	m Number	Mfr Item Name		Effective Date	Version	N	Manufacturing Site	Weight*	UOM	Unit Type	
MCT61	Me	CT61	DIPB-8				INTE	RNAL PENANG	0.474285	g	Each	
Manufacturing Process Information												
Terminal Finish	Base Alloy	J-STD-0	-STD-020 MSL Rating		Peak Process Body Temperature		Max Time at Peak Temperature		No Ret	No Reflow cycles		
Matte Tin (Sn)	CU Alloy	Not .	Applicable	С			seco		seconds		Not Applicable	

<sup>\*</sup> Required Field

## **RoHS Material Composition Declaration**

Declaration Type \* Custom

RoHS Directive 2011/65/EU **RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.

The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.

RoHS Declaration \*

1 - Item(s) does not contain RoHS restricted substances per the definition above

Supplier Acceptance \* Accepted

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2011/534/EU

None

**Declaration Signature** 

Supplier Signature

DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

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## **Homogeneous Material Composition Declaration for Electronic Products**

Item/SubItem Name DIPB-8

Component	Component Material Weight Jig Substance C		Substance Category	tegory Substance			PPM	
Chip	Other inorganic materials	3.753	Supplier		Gallium Arsenide	0.263	1303-00-0	555
			Supplier		Silicon	3.490	7440-21-3	7358
Coupling Gel	Other Organic Materials	4.384	Supplier		Demethyl Siloxane	0.734	68083-19-2	1548
			Supplier		Silane	2.130	2530-85-0	4491
			Supplier		Titanium Dioxide	1.520	13463-67-7	3205
Die Attach	Other Organic Materials	0.423	Supplier		Acrylic Resin	0.106	54208-63-8	223
			Supplier		Silver	0.317	7440-22-4	668
Encapsulation	Thermoplastics	344.100	В	Antimony/Antimony Compounds	Antimony Trioxide	10.300	1309-64-4	21717
			В	Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	13.700	6386-73-8	28886
			Supplier		Carbon Black	3.441	1333-86-4	7255
			Supplier		Epoxy Resin	79.100	29690-82-2	166777
			Supplier		Silica, vitreous	237.559	60676-86-0	500878
Lead Frame	Copper & its alloys	117.616	Supplier		Copper	114.000	7440-50-8	240362
			Supplier		Iron	2.700	7439-89-6	5693
			Supplier		Phosphorus	0.035	7723-14-0	74
			Supplier		Silver	0.740	7440-22-4	1560
			Supplier		Zinc	0.141	7440-66-6	297
Plating	Other Nonferrous metals & alloys	3.810	Supplier		Tin	3.810	7440-31-5	8033
Wire Bond	Precious metals	0.199	Supplier		Gold	0.199	7440-57-5	420